CLAIMS

What is claimed is:

- 1. A semiconductor device formed by a laser etching process comprising: providing a substrate having a surface; forming resist on at least a portion of the surface; and etching the resist from the surface of the substrate using a laser.
- 2. The method according to claim 1, wherein said laser comprises a laser associated with an automolding system.
- 3. The method according to claim 1, wherein said laser includes one of an Nd:YAG laser and an excimer laser.
- 4. The method according to claim 1, wherein said substrate comprises a ball-grid-array substrate.
- 5. The method according to claim 1, further comprising a vision system for detecting resist.
- 6. The method according to claim 5, wherein said vision system comprises: providing a laser scanning system; and detecting changes in a pattern of the substrate.
- 7. A method of enhancing the adhesion of a compound to a surface of a substrate comprising:
 providing said substrate having said surface; and roughening the surface of the substrate.

- 8. The method according to claim 7, wherein said roughening comprises removing contamination and foreign particles from said surface of the substrate.
- 9. An automolding system comprising: providing a substrate having a surface; preheating the substrate; forming a resist layer; baking the substrate; and removing contaminants from the substrate using a laser.
- 10. The automolding system of claim 9, wherein said laser comprises one of an Nd:YAG laser and an excimer laser.
- 11. The automolding system of claim 9, further comprising: placing the substrate in a mold; and encapsulating the substrate.
- 12. A semiconductor device formed by a laser etching process on a substrate having a surface comprising: forming resist on at least a portion of the surface; and etching the resist from the surface of the substrate using a laser.
- 13. The method according to claim 12, wherein said laser comprises a laser associated with an automolding system.
- 14. The method according to claim 12, wherein said laser includes one of an Nd:YAG laser and an excimer laser.

- 15. The method according to claim 12, wherein said substrate comprises a ball-grid-array substrate.
- 16. The method according to claim 12, further comprising a vision system for detecting resist.
- 17. The method according to claim 16, wherein said vision system comprises: providing a laser scanning system; and detecting changes in a pattern of the substrate.